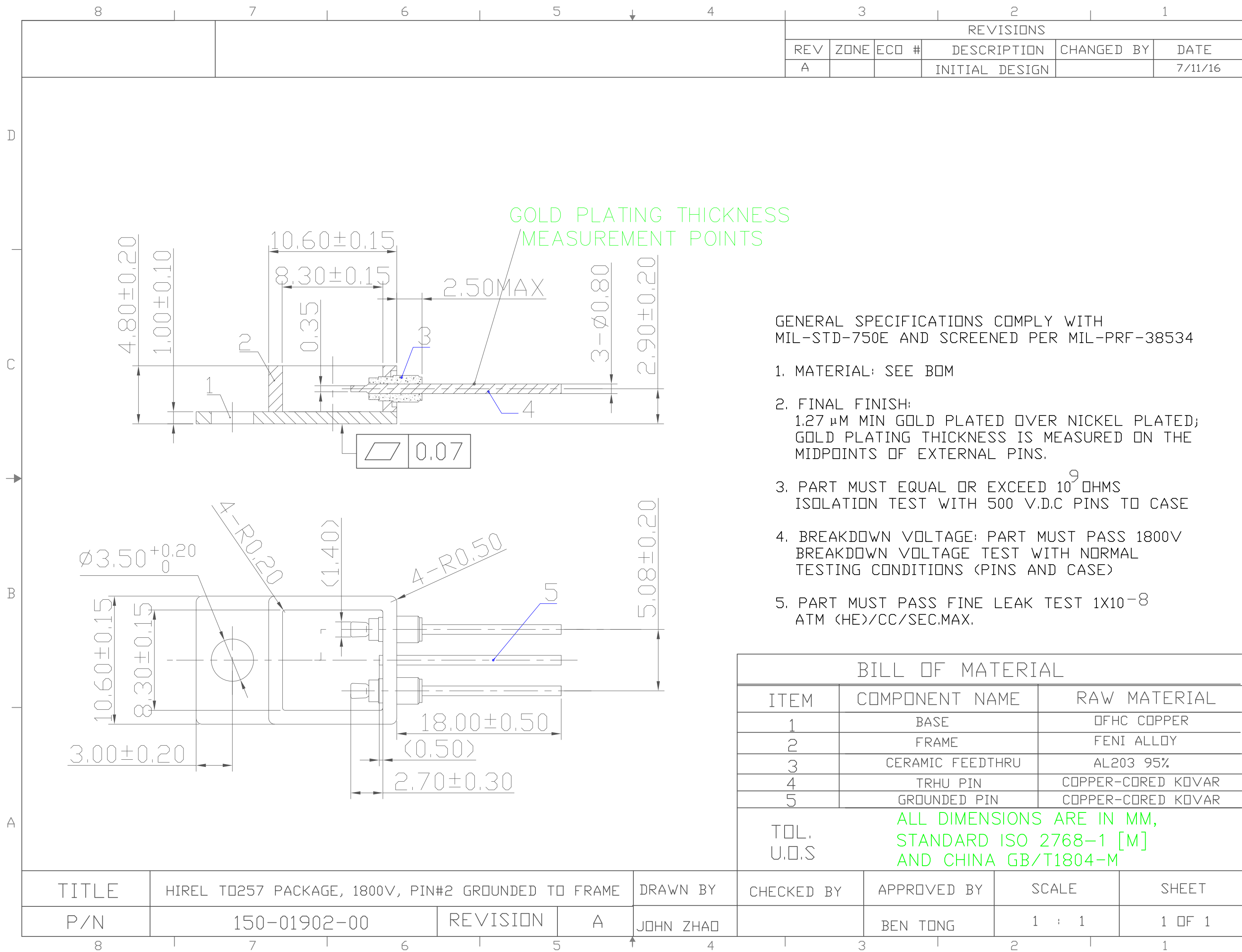


SSM P/N HDR25708



REVISIONS					
REV	ZONE	ECD #	DESCRIPTION	CHANGED BY	DATE
A			INITIAL DESIGN		7/11/16

GENERAL SPECIFICATIONS COMPLY WITH MIL-STD-750E AND SCREENED PER MIL-PRF-38534

1. MATERIAL: SEE BOM
2. FINAL FINISH: 1.27 μM MIN GOLD PLATED OVER NICKEL PLATED; GOLD PLATING THICKNESS IS MEASURED ON THE MIDPOINTS OF EXTERNAL PINS.
3. PART MUST EQUAL OR EXCEED 10⁹ OHMS ISOLATION TEST WITH 500 V.D.C PINS TO CASE
4. BREAKDOWN VOLTAGE: PART MUST PASS 1800V BREAKDOWN VOLTAGE TEST WITH NORMAL TESTING CONDITIONS (PINS AND CASE)
5. PART MUST PASS FINE LEAK TEST 1X10⁻⁸ ATM (HE)/CC/SEC.MAX.

BILL OF MATERIAL		
ITEM	COMPONENT NAME	RAW MATERIAL
1	BASE	OFHC COPPER
2	FRAME	FENI ALLOY
3	CERAMIC FEEDTHRU	AL203 95%
4	TRHU PIN	COPPER-CORED KOVAR
5	GROUNDING PIN	COPPER-CORED KOVAR

TOL. U.D.S
 ALL DIMENSIONS ARE IN MM, STANDARD ISO 2768-1 [M] AND CHINA GB/T1804-M

TITLE	HIREL TO257 PACKAGE, 1800V, PIN#2 GROUNDED TO FRAME		DRAWN BY	CHECKED BY	APPROVED BY	SCALE	SHEET
P/N	150-01902-00	REVISION	A	JOHN ZHAO	BEN TONG	1 : 1	1 OF 1

